

MMIX1T550N055T2

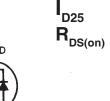
TrenchT2[™] GigaMOS[™] Power MOSFET

(Electrically Isolated Tab)

N-Channel Enhancement Mode Avalanche Rated Fast Intrinsic Diode

| Symbol | Test Conditions | Maximum Ratings | | | |
|-----------------------|--|-----------------|-------|--|--|
| V _{DSS} | $T_{J} = 25^{\circ}C$ to $175^{\circ}C$ | 55 | V | | |
| | T_{J} = 25°C to 175°C, R_{GS} = 1M Ω | 55 | V | | |
| V _{GSM} | Transient | ±20 | V | | |
| I _{D25} | $T_c = 25^{\circ}C$ (Chip Capability) | 550 | A | | |
| I _{DM} | $\rm T_{c}$ = 25°C, Pulse Width Limited by $\rm T_{_{JM}}$ | 2000 | Α | | |
| I _A | $T_c = 25^{\circ}C$ | 200 | А | | |
| E _{AS} | $T_c = 25^{\circ}C$ | 3 | J | | |
| P _D | $T_c = 25^{\circ}C$ | 830 | W | | |
| T, | | -55 +175 | °C | | |
| T _{JM} | | 175 | °C | | |
| T _{stg} | | -55 +175 | °C | | |
| TL | 1.6mm (0.062 in.) from Case for 10s | 300 | °C | | |
| | Plastic Body for 10s | 260 | ۵° | | |
| V _{ISOL} | 50/60 Hz, 1 Minute | 2500 | ٧~ | | |
| F _c | Mounting Force | 50200 / 1145 | N/lb. | | |
| Weight | | 8 | g | | |
| | | | | | |

| SymbolTest ConditionsCha $(T_j = 25^{\circ}C, Unless Otherwise Specified)Min.$ | | | | cteristic Values Typ. Max. | | | |
|--|--|-----|--|-------------------------------|----|--|--|
| BV _{DSS} | $V_{_{\rm GS}} = 0V, I_{_{\rm D}} = 250 \mu A$ | 55 | | | V | | |
| V _{GS(th)} | $V_{_{DS}} = V_{_{GS}}, I_{_{D}} = 250 \mu A$ | 1.8 | | 3.8 | V | | |
| I _{GSS} | $V_{gS} = \pm 20V, V_{DS} = 0V$ | | | ±200 | nA | | |
| I _{DSS} | $V_{DS} = V_{DSS}, V_{GS} = 0V$ | | | 10 | μA | | |
| | T _J = 150°C | ; | | 1.5 | mA | | |
| R _{DS(on)} | $V_{_{\rm GS}}$ = 10V, $I_{_{\rm D}}$ = 100A, Note 1 | | | 1.3 | mΩ | | |



 \mathbf{V}_{dss}

=

=

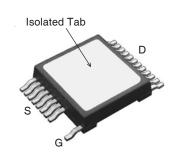
 \leq



55V

550A

1.3mΩ



G = Gate D = DrainS = Source

Features

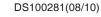
- Silicon Chip on Direct-Copper Bond (DCB) Substrate
- Isolated Substrate
- Excellent Thermal Transfer
- Increased Temperature and Power Cycling Capability
- High Isolation Voltage (2500V~)
- 175°C Operating Temperature
- Very High Current Handling Capability
- Fast Intrinsic Diode
- Avalanche Rated
- Very Low R_{DS(on)}

Advantages

- · Easy to Mount
- Space Savings
- High Power Density

Applications

- DC-DC Converters and Off-Line UPS
- Primary-Side Switch
- High Speed Power Switching Applications



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| Symbol (T _J = 25°C | cteristic Typ. | Values Max. | | | |
|---|-------------------|---|----|------|-----------|
| 9 _{fs} | | $V_{_{DS}} = 10V, I_{_{D}} = 60A, \text{ Note } 1$ | 90 | 150 | S |
| C _{iss} |) | | | 40 | nF |
| C _{oss} | } | $V_{gS} = 0V, V_{DS} = 25V, f = 1MHz$ | | 4970 | pF |
| C _{rss} | J | | | 1020 | pF |
| R _{GI} | | Gate Input Resistance | | 1.36 | Ω |
| t _{d(on)} |) | Resistive Switching Times | | 45 | ns |
| t _r | | $V_{gs} = 10V, V_{ps} = 0.5 \cdot V_{pss}, I_{p} = 200A$ | | 40 | ns |
| t _{d(off)} | (| $R_{\alpha} = 1\Omega$ (External) | 90 | ns | |
| t _f | J | u v z | | 230 | ns |
| Q _{g(on)} |) | | | 595 | nC |
| \mathbf{Q}_{gs} | } | $V_{_{\mathrm{GS}}} = 10V, V_{_{\mathrm{DS}}} = 0.5 \bullet V_{_{\mathrm{DSS}}}, I_{_{\mathrm{D}}} = 0.5 \bullet I_{_{\mathrm{DSS}}}$ | | 150 | nC |
| Q _{gd} | J | | | 163 | nC |
| R _{thJC} | | | | | 0.18 °C/W |
| R _{thCS} | | | | 0.05 | °C/W |

Source-Drain Diode

| SymbolTest ConditionsCharac(T_j = 25°C, Unless Otherwise Specified)Min. | | | | c Values Max. | | |
|---|--|--|-----------------|------------------|---------------|--|
| I _s | $V_{gs} = 0V$ | | | 550 | Α | |
| I _{SM} | Repetitive, Pulse Width Limited by $T_{_{JM}}$ | | | 1700 | А | |
| V _{SD} | $I_{_{\rm F}} = 100$ A, $V_{_{ m GS}} = 0$ V, Note 1 | | | 1.2 | V | |
| t _{rr} I _{RM} Q _{RM} | $I_{F} = 100A, V_{GS} = 0V$ -di/dt = 100A/ μ s $V_{R} = 27.5V$ | | 100 5 250 | | ns A nC | |

Note 1. Pulse test, $t \le 300 \mu s$, duty cycle, $d \le 2\%$.

ADVANCE TECHNICAL INFORMATION

The product presented herein is under development. The Technical Specifications offered are derived from a subjective evaluation of the design, based upon prior knowledge and experience, and constitute a "considered reflection" of the anticipated result. IXYS reserves the right to change limits, test conditions, and dimensions without notice.

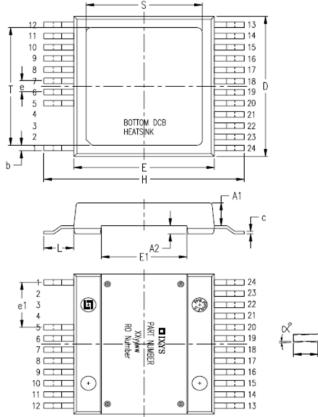
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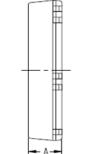
| IX | YS MOSFETs and IGBTs are covered | 4,835,592 | 4,931,844 | 5,049,961 | 5,237,481 | 6,162,665 | 6,404,065 B1 | 6,683,344 | 6,727,585 | 7,005,734 B2 | 7,157,338B2 |
|----|--|-----------|-----------|-----------|-----------|--------------|--------------|-----------|--------------|--------------|-------------|
| by | one or more of the following U.S. patents: | | | | | | - / / | -, -, | - , , | 7,063,975 B2 | |
| | | 4,881,106 | 5,034,796 | 5,187,117 | 5,486,715 | 6,306,728 B1 | 6,583,505 | 6,710,463 | 6,771,478 B2 | 7,071,537 | |

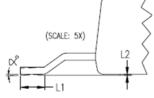


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Package Outline







| SYM | INC | HES | MILLIMETERS | | | |
|-----------|-------|-------|-------------|-------|--|--|
| 21M | MIN | MAX | MIN | MAX | | |
| Α | .209 | .224 | 5.30 | 5.70 | | |
| A1 | .154 | .161 | 3.90 | 4.10 | | |
| A2 | .055 | .063 | 1.40 | 1.60 | | |
| b | .035 | .045 | 0.90 | 1.15 | | |
| С | .018 | .026 | 0.45 | 0.65 | | |
| D | .976 | .994 | 24.80 | 25.25 | | |
| E | .898 | .915 | 22.80 | 23.25 | | |
| E1 | .543 | .559 | 13.80 | 14.20 | | |
| е | .07 | 9 BSC | 2.00 | 0 BSC | | |
| e1 | .31 | 5 BSC | 8.00 |) BSC | | |
| Н | 1.272 | 1.311 | 32.30 | 33.30 | | |
| L | .181 | .209 | 4.60 | 5.30 | | |
| L1 | .051 | .067 | 1.30 | 1.70 | | |
| L2 | .000 | .006 | 0.00 | 0.15 | | |
| S | .736 | .760 | 18.70 | 19.30 | | |
| Т | .815 | .839 | 20.70 | 21.30 | | |
| \propto | 0 | 4' | 0 | 4' | | |

PIN: 1 = Gate 5-12 = Source 13-24 = Drain